

### General Specifications

<b>Resistive Element:</b>	Thick film
<b>Substrate:</b>	Alumina ceramic
<b>Terminals:</b>	Thick film silver
<b>Resistance Value:</b>	50 ohms, ±2%

**Notes:** Tolerance is ±.010, unless otherwise specified. Operating temperature is -55°C to +125°C (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches.

**Specifications subject to change without notice.**

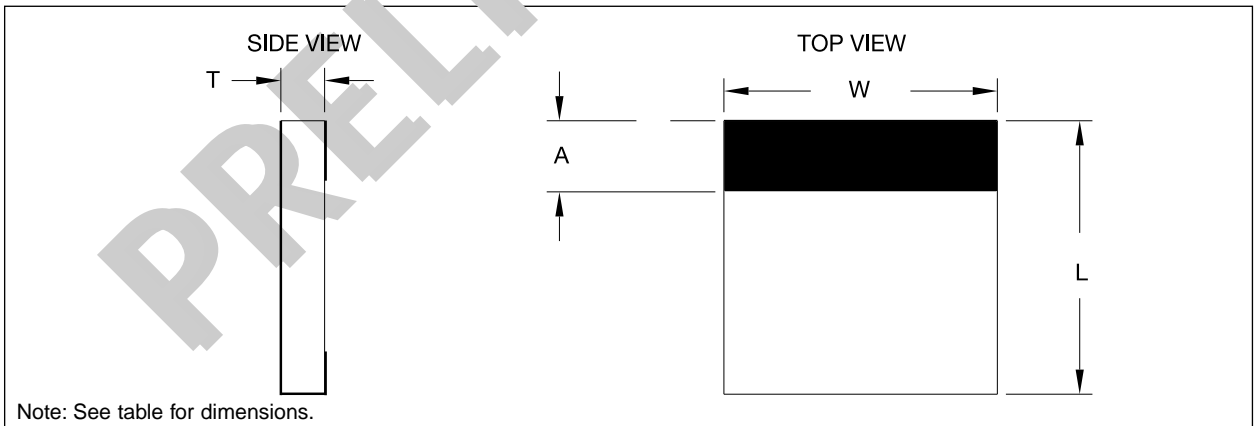
### Features

- DC - 6.0 GHz
- 10-40 Watts
- Low Cost
- Alumina Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

### Dimensions

PART NUMBER	WIDTH	LENGTH	THK.	A
RFP-060120A25X50	0.060	0.120	0.025	0.030
RFP-100200A25X50	0.100	0.200	0.025	0.030
RFP-250250A4X50	0.250	0.250	0.040	0.040
RFP-250375A4X50	0.250	0.375	0.040	0.040
RFP-375250A4X50	0.375	0.250	0.040	0.050
RFP-375375A4X50	0.375	0.375	0.040	0.050

### Outline Drawing



Available on Tape and Reel for Pick and Place Manufacturing.

# Alumina Terminations

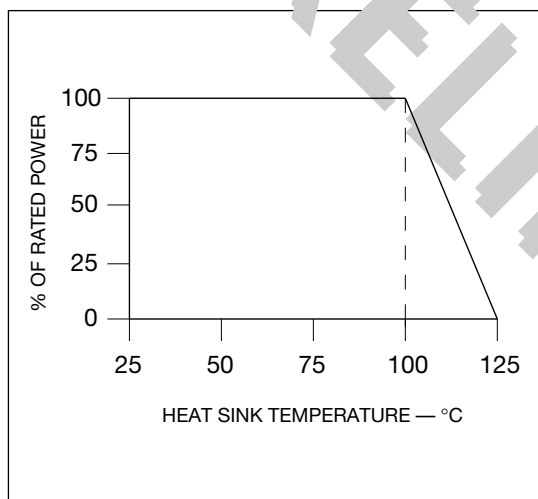
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## RF Power

### Typical Performance

PART NUMBER	VALUE (OHM)	POWER (WATTS)	MAX VSWR	FREQ. (GHz)
RFP-060120A25X50	50	10	1.25:1	6.0
RFP-100200A25X50	50	20	1.25:1	6.0
RFP-250250A4X50	50	30	1.25:1	3.0
RFP-250375A4X50	50	40	1.25:1	3.0
RFP-375250A4X50	50	40	1.20:1	2.5
RFP-375375A4X50	50	40	1.20:1	2.5

### Power Derating



### Suggested Mounting Procedures

**SUGGESTED STRESS RELIEF METHODS**

0.025 MIN. (2 PLACES)

BOARD LOWER THAN LEAD.      BOARD EVEN WITH LEAD.

SCALE: ~~~~~

**NOT RECOMMENDED APPLICATION**

BOARD LOWER THAN LEAD.      BOARD HIGHER THAN LEAD.

SCALE: ~~~~~

1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Position device on mounting surface and solder in place using an indalloy type or an SN63 type solder.
3. Solder leads in place using a 60/40 type solder with a controlled temperature iron (700°F).

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